MA3X1000G

Silicon epitaxial planar type

For switching circuits

■ Features

- High breakdown voltage: $V_R = 200 \text{ V}$
- Small terminal capacitance C_t

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	200	V
Repetitive peak reverse voltage	V _{RRM}	250	V
Forward current (Average)	I _{F(AV)}	100	mA
Repetitive peak forward current	I _{FRM}	225	mA
Non-repetitive peak forward surge current *	I _{FSM}	500	mA
Junction temperature	T_{j}	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *: t = 1 s

Package

- Code
 - SMini3-F2
- Pin Name
 - 1: Anode
 - 2: N.C.
- 3: Cathode
- Marking Symbol: M3A

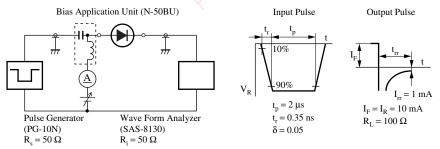
Internal Connection

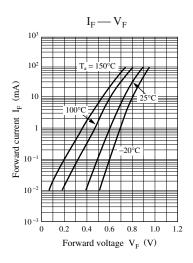


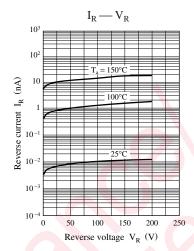
■ Electrical Characteristics T_a = 25°C ± 3°C

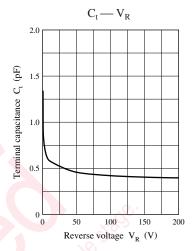
Parameter	Symbol	Conditions	Min Typ	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 100 \text{ mA}$	160	1.2	V
Reverse current	I_R	$V_{R} = 200 \text{ V}$		1.0	μΑ
Terminal capacitance	C _t	$V_R = 0 V, f = 1 MHz$		3.0	pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 10 \text{ mA}$		60	ns
		$I_{rr} = 1 \text{ mA}$, $R_L = 100 \Omega$			

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. Absolute frequency of input and output is 20 MHz.
 - 3. *: t_{rr} measurement circuit



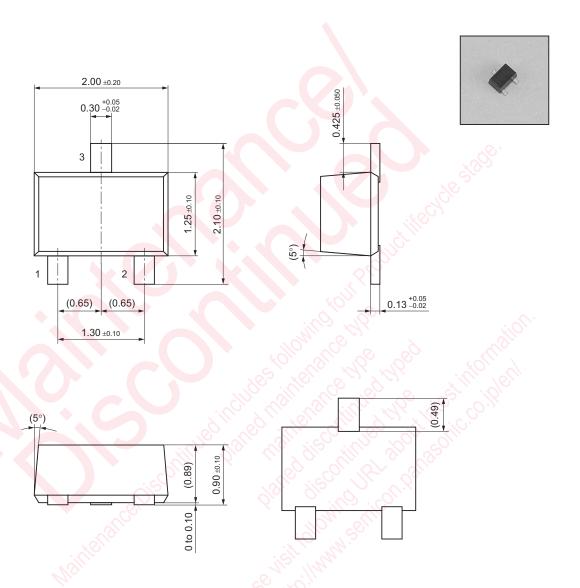






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SMini3-F2 Unit: mm



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